

L Number	Hits	Search Text	DB	Time stamp
-	1752	((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.	USPAT; US-PGPUB	2003/10/14 08:06
-	11	((43/460) or (438/463) or (438/606) or (438/107) or (438/620) or (438/712) or (438/718) or (438/728) or (438/733) or (738/742)).CCLS.) and (thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/21 09:50
-	260	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT; US-PGPUB	2003/07/22 10:09
-	11	("5096854"   "5213657"   "5840614"   "5891298"   "5968849"   "5981391"   "6017822"   "6020252"   "6033995"   "6046117"   "6100166").PN.	USPAT	2003/07/21 09:48
-	0	6162702.URPN.	USPAT	2003/07/21 09:49
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 09:51
-	15144	radio with frequency with circuit	USPAT; US-PGPUB	2003/07/21 09:51
-	0	((thinning with (substrate wafer))) with (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	27	((thinning with (substrate wafer))) and (radio with frequency with circuit)	USPAT; US-PGPUB	2003/07/21 09:52
-	7	5336930.URPN.	USPAT	2003/07/21 10:02
-	13	5221221.URPN.	USPAT	2003/07/21 10:19
-	7	5336930.URPN.	USPAT	2003/07/21 10:20
-	9	("3648131"   "4447291"   "4507674"   "4789645"   "4849376"   "4965218"   "4970578"   "4972250"   "4977100").PN.	USPAT	2003/07/21 10:21
-	10	4970578.URPN.	USPAT	2003/07/21 10:22
-	10	4970578.URPN.	USPAT	2003/07/21 10:29
-	14	("3986196"   "4091408"   "4374394"   "4376287"   "4571611"   "4601096"   "4751562"   "4794093"   "4807022"   "4818724"   "4823174"   "4827610"   "4868613"   "4896194").PN.	USPAT	2003/07/21 10:30
-	12	4868613.URPN.	USPAT	2003/07/21 10:32
-	12	5064772.URPN.	USPAT	2003/07/21 10:35
-	0	mmic with thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 10:35
-	0	mmic and (thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:36
-	7	(thining with (substrate wafer))	USPAT; US-PGPUB	2003/07/21 10:37
-	2618	(thinning with (substrate wafer))	USPAT; US-PGPUB	2003/07/22 10:10
-	29	((thinning with (substrate wafer))) and mmic	USPAT; US-PGPUB	2003/07/21 10:38
-	0	10034723.pn.	USPAT; US-PGPUB	2003/07/21 11:38
-	0	"10034723"	USPAT; US-PGPUB	2003/07/21 11:41
-	0	((thinning with (substrate wafer))) and vernier with marker	USPAT; US-PGPUB	2003/07/21 11:41
-	48	vernier with marker	USPAT; US-PGPUB	2003/07/21 11:48
-	438	438/462.ccls.	USPAT; US-PGPUB	2003/07/21 11:49
-	41	438/462.ccls. and thinning with (substrate wafer)	USPAT; US-PGPUB	2003/07/21 11:51
-	0	438/462.ccls. and mmisc	USPAT; US-PGPUB	2003/07/21 11:51
-	7	438/462.ccls. and mmic	USPAT; US-PGPUB	2003/07/21 11:52
-	29	438/462.ccls. and depth with mark	USPAT; US-PGPUB	2003/07/21 12:03
-	2	438/462.ccls. and backside and (depth with mark)	USPAT; US-PGPUB	2003/07/21 12:04

-	12	438/462.ccls. and backside and ((alignment depth) with mark)	USPAT;	2003/07/21 13:03
-	0	"09034747"	US-PGPUB	2003/07/21 13:05
-	0	"10034747"	USPAT;	2003/07/21 13:05
-	2	measured with via with etch with etching	US-PGPUB	2003/07/21 13:05
-	0	(measured with via with hole with etching) and bernier	USPAT;	2003/07/21 13:06
-	0	(measured with via with hole with etching) and vernier	US-PGPUB	2003/07/21 13:06
-	6	measured with via with hole with etching	USPAT;	2003/07/21 13:06
-	1945	hemt	US-PGPUB	2003/07/22 08:50
-	382	hemt and mmic	USPAT;	2003/07/22 08:50
-	117	(hemt and mmic) and pad	US-PGPUB	2003/07/22 08:50
-	0	((hemt and mmic) and pad) and thinning with (substrate wafer)	USPAT;	2003/07/22 08:57
-	37	((hemt and mmic) and pad) and (thin thins thinning) with (substrate wafer)	US-PGPUB	2003/07/22 08:59
-	87	(hemt and mmic) and mmic and ((source and drain) with region)	USPAT;	2003/07/22 09:01
-	21	((hemt and mmic) and mmic and ((source and drain) with region)) and ((source and drain) with pad)	US-PGPUB	2003/07/22 09:01
-	261	(thinning with (substrate wafer)) and ("grid" "waffle")	USPAT;	2003/07/22 10:10
-	2624	(thinning with (substrate wafer))	US-PGPUB	2003/07/22 10:10
-	22264	metal with mask	USPAT;	2003/07/22 10:11
-	14	((thinning with (substrate wafer)) ) with (metal with mask)	US-PGPUB	2003/07/22 10:11
-	1708	uchiyama.inv.	USPAT;	2003/10/06 14:12
-	1079	uchiyama.inv. and (hole via trench opening)	US-PGPUB	2003/10/06 14:12
-	257	(uchiyama.inv. and (hole via trench opening)) and (substrate wafer)	USPAT;	2003/10/06 14:14
-	43	((uchiyama.inv. and (hole via trench opening)) and (substrate wafer)) and hiroyuki.inv.	US-PGPUB	2003/10/06 14:15
-	109	uchiyama.inv. and hiroyuki.inv.	USPAT;	2003/10/06 14:20
-	188	(438/667).CCLS.	US-PGPUB	2003/10/06 14:20
-	4	("5243498"   "5434094"   "5488253"   "5646067").PN.	USPAT	2003/10/06 14:45
-	16	5322816.URPN.	USPAT	2003/10/06 14:56
-	4	("5243498"   "5434094"   "5488253"   "5646067").PN.	USPAT	2003/10/06 14:58
-	0	6365513.URPN.	USPAT	2003/10/06 14:58
-	54	("5046239"   "5063177"   "5172050"   "5229647"   "5236551"   "5249450"   "5404044"   "5420520"   "5426072"   "5483741"   "5484647"   "5487999"   "5528080"   "5541525"   "5557844"   "5578526"   "5592736"   "5607818"   "5633122"   "5634267"   "5674785"   "5686317"   "5716218"   "5781022"   "5783461"   "5783865"   "5796590"   "5801452"   "5815000"   "5834945"   "5869974"   "5876580"   "5878485"   "5896036"   "5915977"   "5929647"   "5931685"   "5936847"   "5952840"   "5962921"   "6013948"   "6040702"   "6107109"   "6107119"   "6114240"   "6162997"   "6294837"   "6353328"   "6356098"   "6362637"   "6400172"   "6417685"   "6437591"   "6451624").PN.	USPAT	2003/10/06 15:00
-	29	5528080.URPN.	USPAT	2003/10/06 15:04

-	15	("2770761"   "3895967"   "3897361"   "3904442"   "3979820"   "4074342"   "4239312"   "4275410"   "4370179"   "4535424"   "4660066"   "4720308"   "4761681"   "4773972"   "4860084").PN.	USPAT	2003/10/06 15:09
-	0	438/667.clas.	USPAT; US-PGPUB	2003/10/07 08:30
-	0	438/667.class	USPAT; US-PGPUB	2003/10/07 08:30
-	0	438/667.ccls/	USPAT; US-PGPUB	2003/10/07 08:30
-	188	438/667.ccls.	USPAT; US-PGPUB	2003/10/07 08:30
-	6	438/667.ccls. and (ecr ocp)	USPAT; US-PGPUB	2003/10/07 08:30
-	8	438/667.ccls. and (ecr icp)	USPAT; US-PGPUB	2003/10/07 08:50
-	786	((438/113) or (438/464)).CCLS.	USPAT; US-PGPUB	2003/10/07 08:51
-	0	((438/113) or (438/464)).CCLS.) and ((substrate wafer) with (segregation))	USPAT; US-PGPUB	2003/10/07 08:52
-	441	((substrate wafer) with (segregation))	USPAT; US-PGPUB	2003/10/07 08:52
-	0	((438/113) or (438/464)).CCLS.) and ((substrate wafer) with (segregation)))	USPAT; US-PGPUB	2003/10/07 08:52
-	170	((substrate wafer) with (segregation))) and ((438/\$).ccls.)	USPAT; US-PGPUB	2003/10/07 08:54
-	44	((438/113) or (438/464)).CCLS.) and (mount\$4 with front\$3)	USPAT; US-PGPUB	2003/10/07 10:01
-	563	(438/459).CCLS.	USPAT; US-PGPUB	2003/10/07 10:02
-	535	(438/460).CCLS.	USPAT; US-PGPUB	2003/10/07 10:02
-	2	((438/459).CCLS.) and mmic	USPAT; US-PGPUB	2003/10/07 10:02
-	7	((438/460).CCLS.) and mmic	USPAT; US-PGPUB	2003/10/07 10:04
-	0	((438/460).CCLS.) and mmic) and (ecr icp)	USPAT; US-PGPUB	2003/10/07 10:04
-	188	(438/667).CCLS.	USPAT; US-PGPUB	2003/10/14 08:06
-	50	((438/667).CCLS.) and (metal with mask\$3)	USPAT; US-PGPUB	2003/10/14 08:07